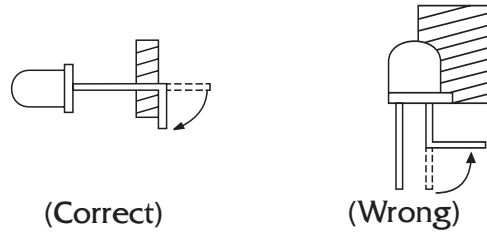


The Following Precautions must be taken to protect the reliability of led products.

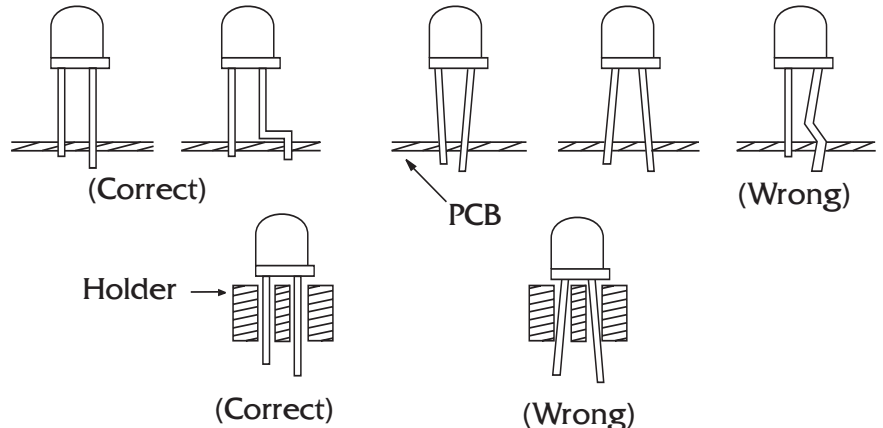
### (1) FORMING:

- a. Please don't form the LED after soldering. If forming is necessary, it must be done before soldering.
- b. Any unsuitable stress applied to the epoxy body may break bonding wires in LED.



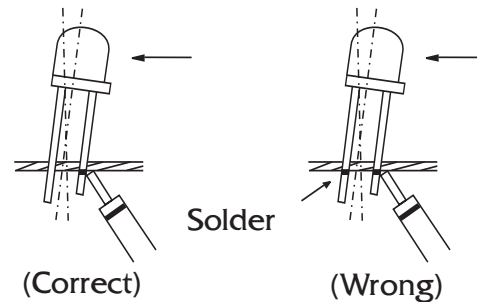
### (2) INSTALLATION:

- a. Do not apply physical stress to the leads when mounting led lamps on PCB.
- b. Installation with holder - The holder should be designed not to subject leads to any stress.



### (3) SOLDERING:

- a. Do not dip epoxy body into solder bath.
- b. Do not apply stress to leads while they are heated.
- c. Acceptable soldering condition.



KINDS OF SOLDERING		CONDITIONS
SOLDER IRON		300 C + 5 C, WITHIN 3 SECONDS (1.6mm FROM EPOXY BODY)
SOLDER BATH		260 C + 5 C, WITHIN 5 SECONDS (1.6mm FROM EPOXY BODY)
REFLOW SOLDERING	PRE HEATING	75 C + 5 C, WITHIN 30 SECONDS
	SOLDERING	245 C + 5 C, WITHIN 5 SECONDS (1.6mm FROM EPOXY BODY)

### (4) CLEANING:

- a. In any case, the dipping or steam cleaning time should be one (1) minute or less, a normal temperature.
- b. When cleaning is required, please refer to the following table.

ACCEPTABLE SOLVENT	FORBIDDEN
Alcohol	thinner, acetone, freon tmc, diflon S3MC, trichloroethylene, chlorosen.

- c. Do not clean leds with water as the remains may rust the leads.
- d. Leds may be damaged in an ultrasonic cleaning process. A sample led should be cleaned prior to mass cleaning to assure integrity.